FALIT FS Laser Decapsulation System

Capability/Application
Laser decapsulation is a technique which can locally remove the molding material without damaging the overall functionality of the chip. Compared to chemical decapsulation technique, Laser decapsulation is more efficient and reduce the exposure to strong acid etching environments.

Specifications
Cross-section Laser Cut module:
Model: Draco-51S40A Green Laser
Wavelength: 532nm
Average Output Power: >10W at 40kHz
Pulse Width: <30ns at 30kHz

Laser Decap module:
Model: Harrier-1064-14-L-V3 IR laser
Wavelength: 1064nm
Average Output Power: >12W at 10KHz
Pulse Width: <40ns at 10KHz
Example application images

5x5 QFN decapsulation

SOT23-6 decapsulation

Equipment manufacturer web page

Youtube demo videos
https://www.youtube.com/watch?v=L1b__2FrT4s